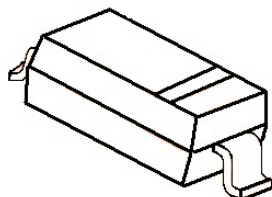


SOD-123



特征 Features

齐纳击穿阻抗低; Low Zener Impedance
最大功率耗散 500mW; Power Dissipation of 500mW
高稳定性和可靠性。High Stability and High Reliability

机械数据 Mechanical Data

封装: SOD-123 封装 SOD-123 Small Outline Plastic Package
极性: 色环端为负极 Polarity: Color band denotes cathode end
环氧树脂 UL 易燃等级 Epoxy UL: 94V-0
安装位置: 任意 Mounting Position: Any

极限值和温度特性(TA = 25°C 除非另有规定)

Maximum Ratings & Thermal Characteristics (Ratings at 25°C ambient temperature unless otherwise specified.)

参数 Parameters	符号 Symbol	数值 Value	单位 Unit
功率消耗 Power Dissipation	Pd	500 ¹⁾	mW
正向压降 Forward Voltage @IF=10mA	Vf	0.9 ²⁾	V
热阻 Thermal Resistance, Junction to Ambient Air	R _{θJA}	357	°C/W
工作结温 Junction/Operating Temperature	Tj	150	°C
存储温度 Storage temperature range	Ts	-65-+150	°C

1) Device mounted on ceramic PCB: 7.6mm x 9.4mm x 0.87mm with pad areas 25mm²

2) Short duration test pulse used to minimize self-heating effect

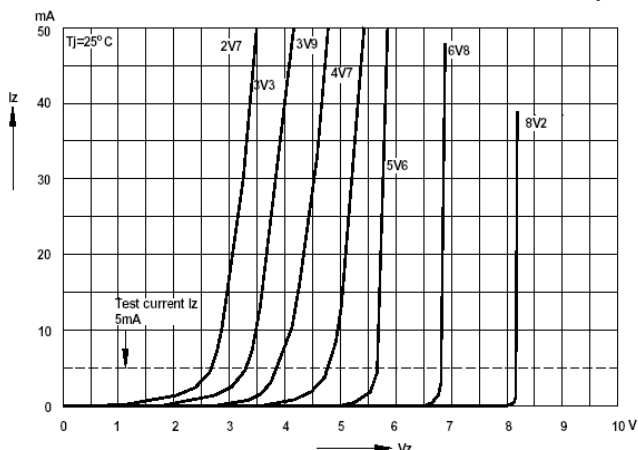
3) f=1KHz

电特性 (TA = 25°C 除非另有规定) **Electrical Characteristics** (Ratings at 25°C ambient temperature unless otherwise specified).

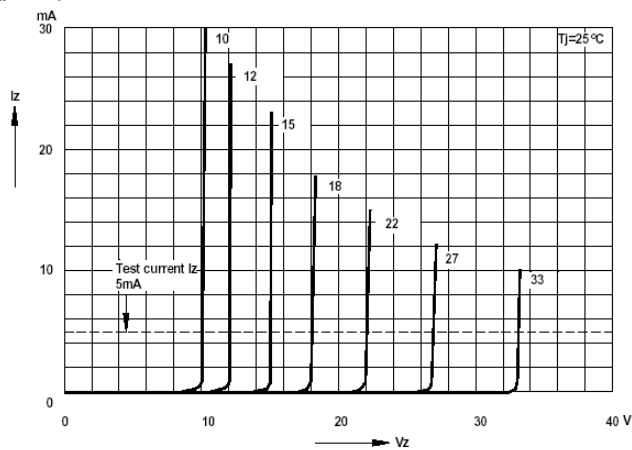
Device	Marking	Zener Voltage Range				Maximum Zener Impedance			Maximum Reverse Current		Typical Temperature coefficient @ IZTC=mV/°C		Test Current IZTC
		Vz@Izt			Izt	Zzt @Izt	Zzk @Izk	Izk	IR	VR	Min	Max	
		Nom(V)	Min(V)	Max(V)	mA	Ω			mA	uA			V
MMSZ5231B-7-F-CN	2W8	5.1	5.00	5.20	5	60	480	1.0	2	2.0	-2.7	1.2	5

Breakdown characteristics

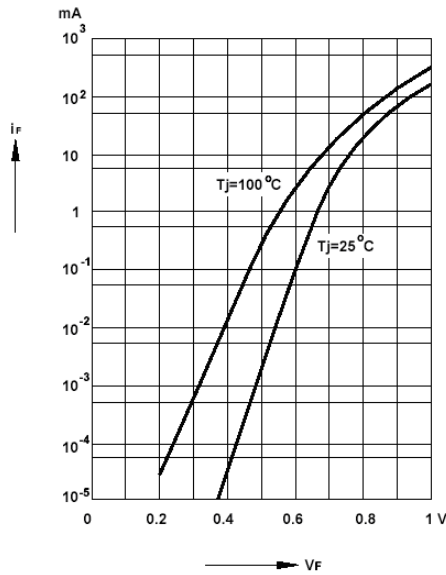
at Tj=constant (pulsed)



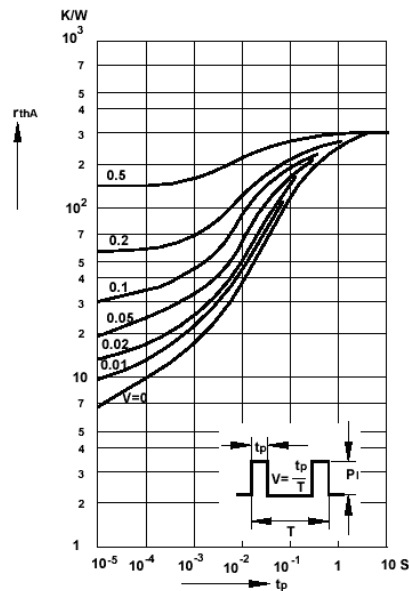
Forward characteristics



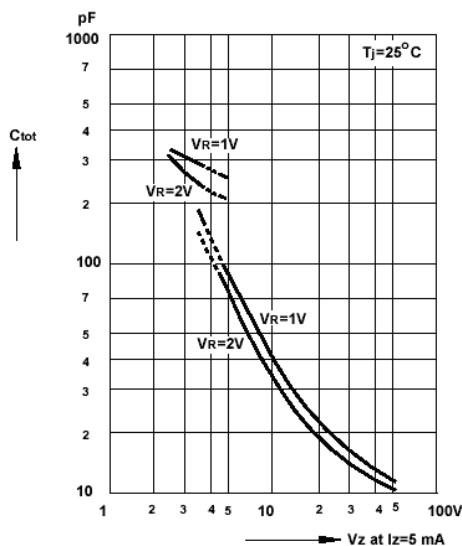
Admissible power dissipation versus ambient temperature



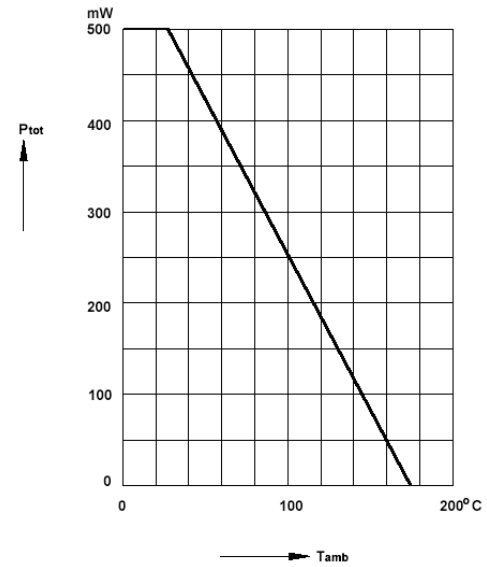
Pulse thermal resistance versus pulse duration



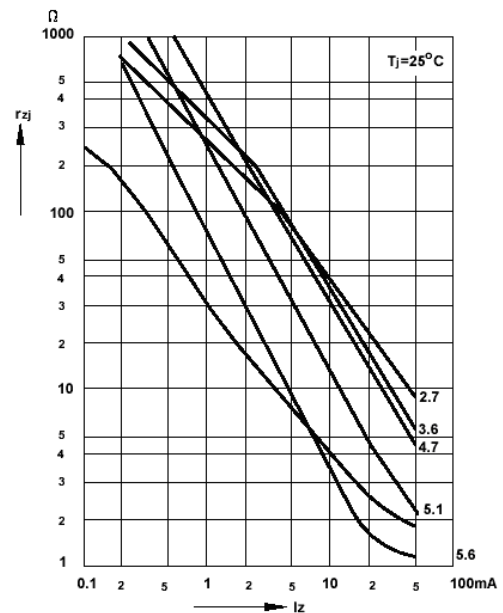
Capacitance versus Zener voltage



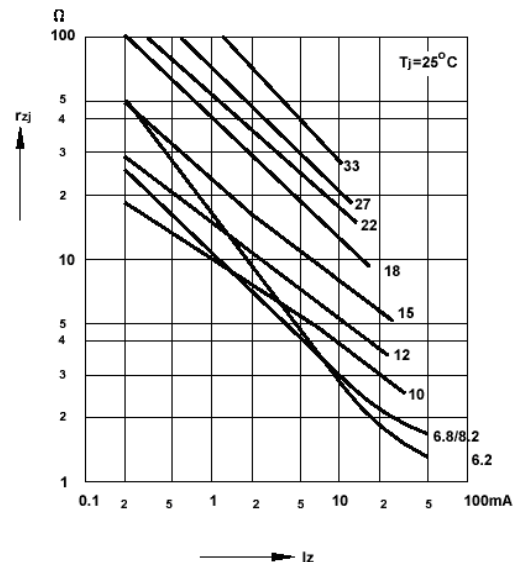
Dynamic resistance versus Zener current



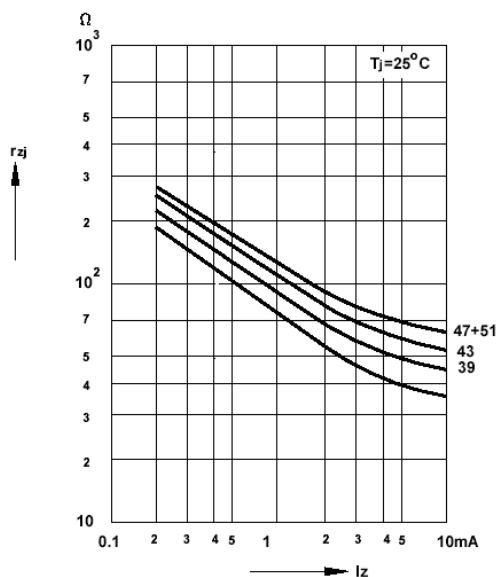
Dynamic resistance versus Zener current



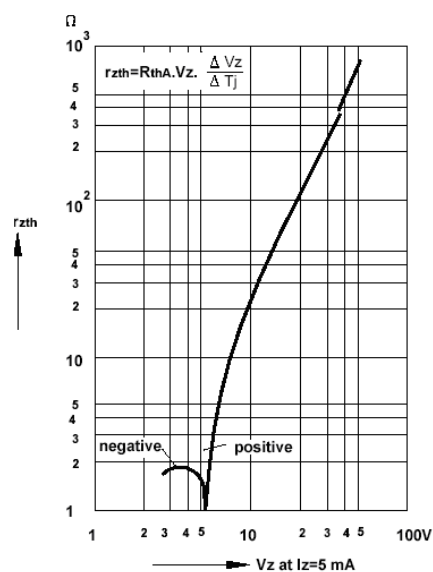
Dynamic resistance versus Zener current



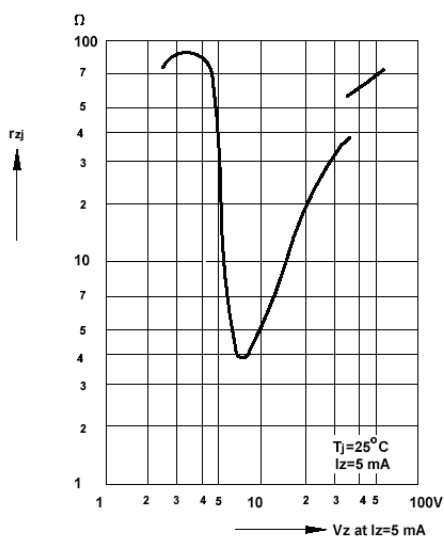
Thermal differential resistance versus Zener voltage



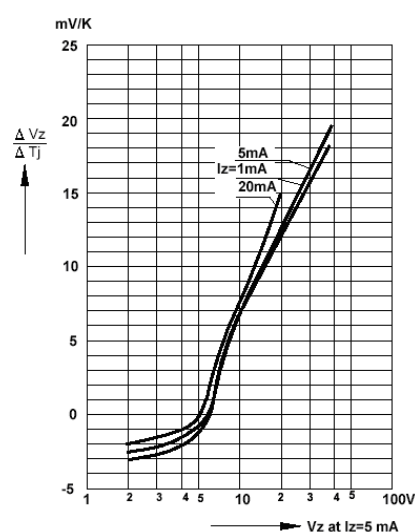
Dynamic resistance versus Zener voltage



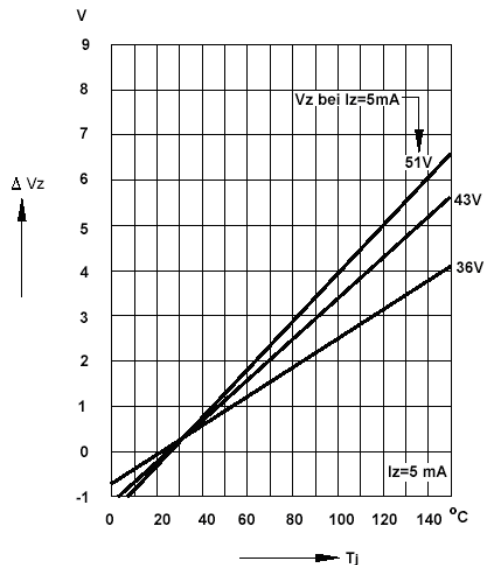
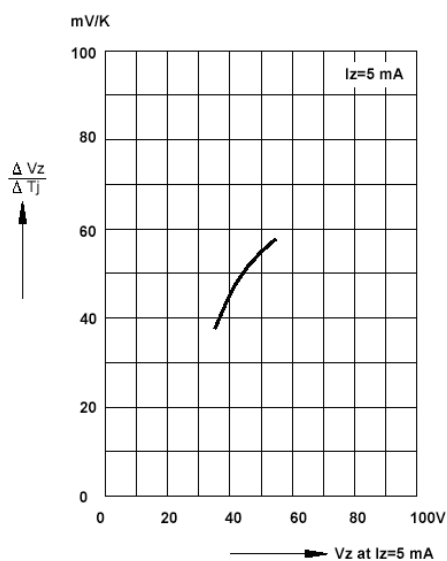
Temperature dependence of Zener voltage versus Zener voltage



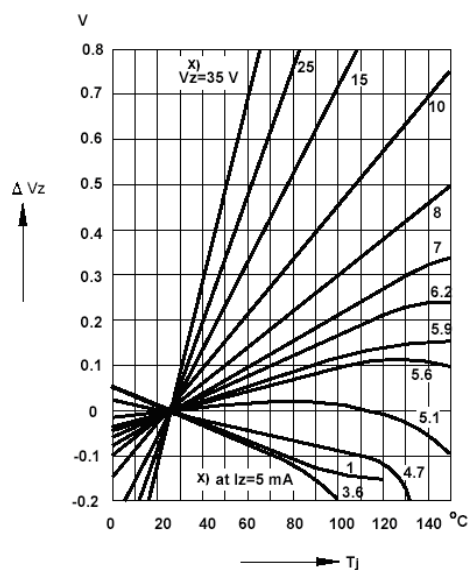
Temperature dependence of Zener voltage versus Zener voltage



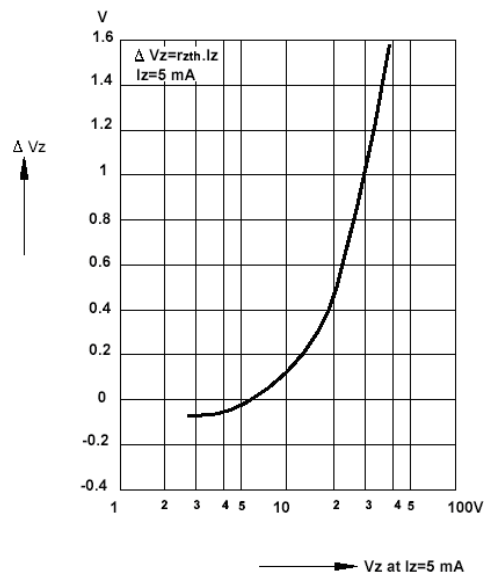
Change of Zener voltage versus junction temperature



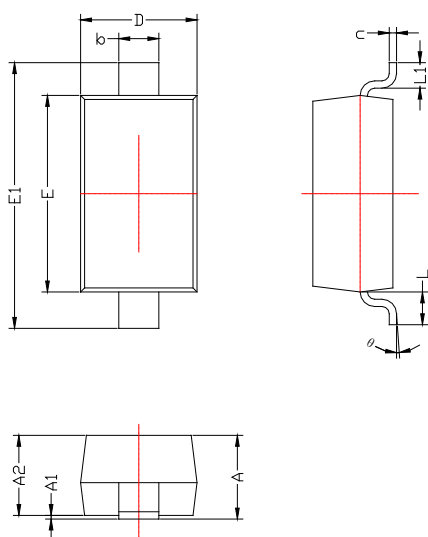
Change of Zener voltage versus junction temperature



Change of Zener voltage from turn-on up to the point of thermal equilibrium versus Zener voltage



SOD-123 PACKAGE OUTLINE Plastic surface mounted package

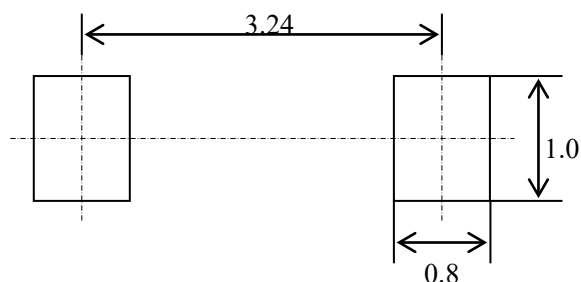


SYMBOL	DIMENSIONS	
	MIN.	MAX.
A	1.050	1.250
A1	0.000	0.100
A2	1.050	1.150
b	0.450	0.650
c	0.080	0.150
D	1.500	1.700
E	2.600	2.800
E1	3.550	3.850
L	0.500REF	
L1	0.250	0.450
θ	0°	8°

焊盘设计参考

Precautions: PCB Design

Recommended land dimensions for SOD-123 diode. Electrode patterns for PCBs



中心距: 3.24

脚 宽: 0.55

焊盘宽: 1.00

脚 长: 0.50

焊盘长: 0.80

技术要求:

1, 塑封体尺寸: 2.70 X 1.60

2, 未注公差为: ± 0.05

3, 所有单位: mm

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